

N-channel 30 V, 0.0038 Ω typ., 17 A STripFET™ VI DeepGATE™ Power MOSFET in a PowerFLAT™ 3.3 x 3.3 package

Datasheet - production data

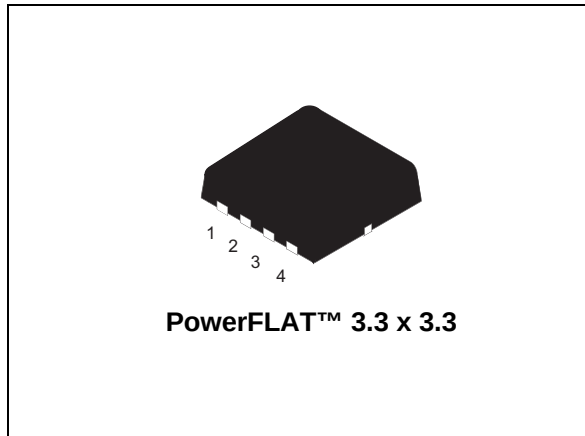
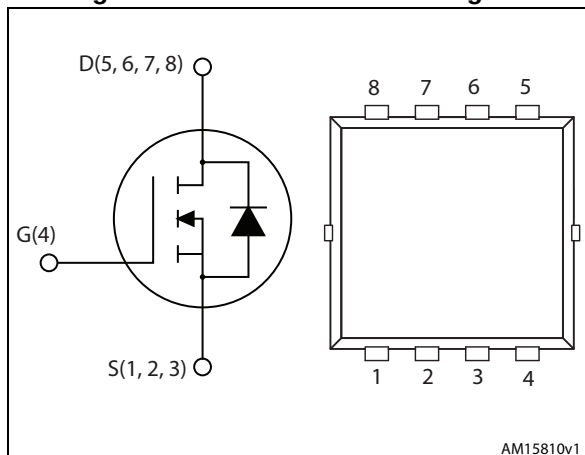


Figure 1. Internal schematic diagram



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STL17N3LLH6	30 V	0.0045 Ω	17 A ⁽¹⁾

1. The value is rated according $R_{thj-pcb}$.

- $R_{DS(on)} * Q_g$ industry benchmark
- Extremely low on-resistance $R_{DS(on)}$
- High avalanche ruggedness
- Low gate drive power losses
- Very low switching gate charge

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using the 6th generation of STripFET™ DeepGATE™ technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest $R_{DS(on)}$ in all packages.

Table 1. Device summary

Order code	Marking	Package	Packaging
STL17N3LLH6	17N3L	PowerFLAT™ 3.3 x 3.3	Tape and reel

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	30	V
V_{GS}	Gate-source voltage	± 20	V
$I_D^{(1)}$	Drain current (continuous) at $T_{pcb} = 25\text{ °C}$	17	A
$I_D^{(1)}$	Drain current (continuous) at $T_{pcb} = 100\text{ °C}$	11	A
$I_{DM}^{(2)}$	Drain current (pulsed)	68	A
$P_{TOT}^{(3)}$	Total dissipation at $T_C = 25\text{ °C}$	50	W
$P_{TOT}^{(1)}$	Total dissipation at $T_{pcb} = 25\text{ °C}$	2	W
	Derating factor	0.03	W/°C
T_J	Operating junction temperature	-55 to 150	°C
T_{stg}	Storage temperature		°C

1. The value is rated according $R_{thj-pcb}$.
2. Pulse width limited by safe operating area.
3. The value is rated according R_{thj-c} .

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{thj-case}^{(2)}$	Thermal resistance junction-case	2.5	°C/W
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	42.8	°C/W
$R_{thj-pcb}^{(2)}$	Thermal resistance junction-pcb	63.5	°C/W

1. When mounted on FR-4 board of 1inch², 2oz Cu, $t < 10\text{ sec}$.
2. Steady state.

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0$	30			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0$, $V_{DS} = 30\text{ V}$			1	μA
		$V_{GS} = 0$, $V_{DS} = 30\text{ V}$, $T_C = 125\text{ °C}$			10	μA
I_{GSS}	Gate body leakage current	$V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	1			V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 8.5\text{ A}$		0.0038	0.0045	Ω
		$V_{GS} = 4.5\text{ V}$, $I_D = 8.5\text{ A}$		0.0057	0.0073	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 24\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$	-	1690	-	pF
C_{oss}	Output capacitance		-	290	-	pF
C_{rss}	Reverse transfer capacitance		-	176	-	pF
Q_g	Total gate charge	$V_{DD} = 24\text{ V}$, $I_D = 17\text{ A}$ $V_{GS} = 4.5\text{ V}$ (see Figure 14)	-	17	-	nC
Q_{gs}	Gate-source charge		-	8	-	nC
Q_{gd}	Gate-drain charge		-	6	-	nC
R_G	Gate input resistance	$f = 1\text{ MHz}$ Gate DC Bias = 0 Test signal level = 20 mV open drain	-	1.7	-	Ω

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 24\text{ V}$, $I_D = 8.5\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ (see Figure 13)	-	9.5	-	ns
t_r	Rise time		-	30	-	ns
$t_{d(off)}$	Turn-off delay time		-	37	-	ns
t_f	Fall time		-	12	-	ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min	Typ.	Max	Unit
I_{SD}	Source-drain current		-		17	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		68	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 17\text{ A}$, $V_{GS} = 0$	-		1.1	V
t_{rr}	Reverse recovery time	$I_{SD} = 17\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 24\text{ V}$	-	24		ns
Q_{rr}	Reverse recovery charge		-	16.8		nC
I_{RRM}	Reverse recovery current		-	1.4		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration=300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

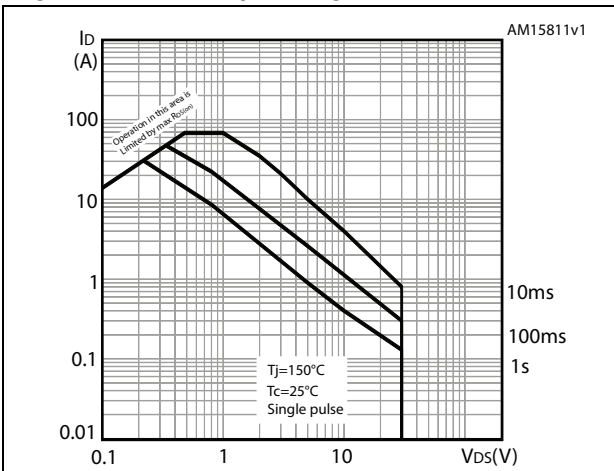


Figure 3. Thermal impedance

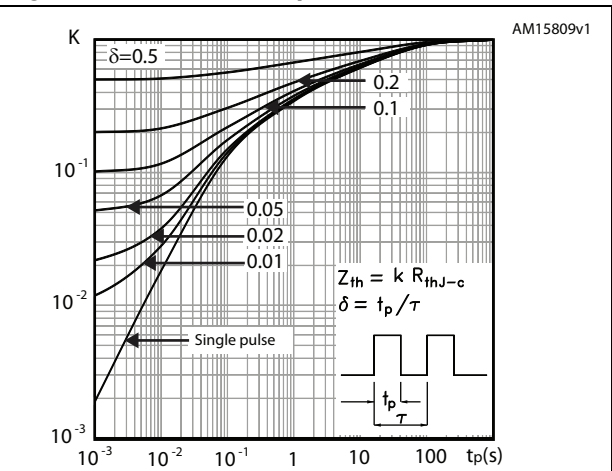


Figure 4. Output characteristics

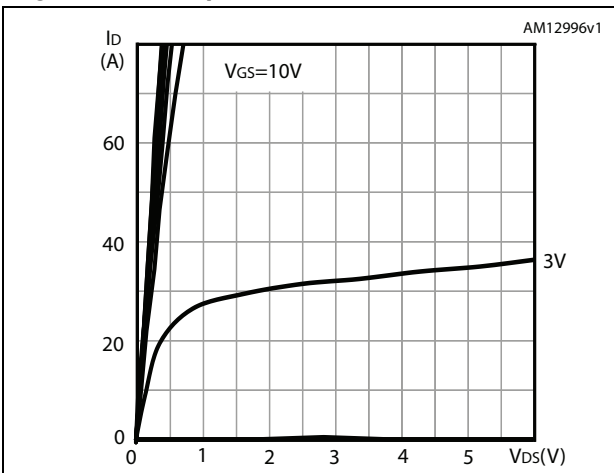


Figure 5. Transfer characteristics

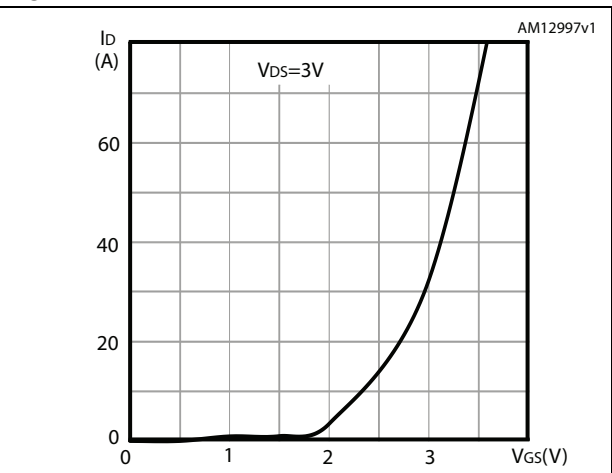


Figure 6. Normalized BV_{DSS} vs temperature

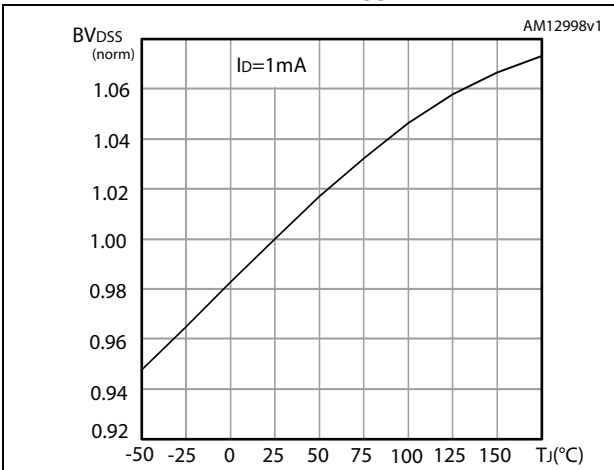


Figure 7. Static drain-source on-resistance

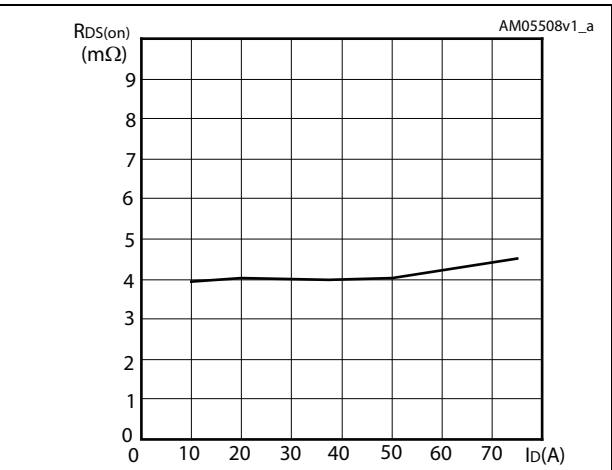


Figure 8. Gate charge vs gate-source voltage

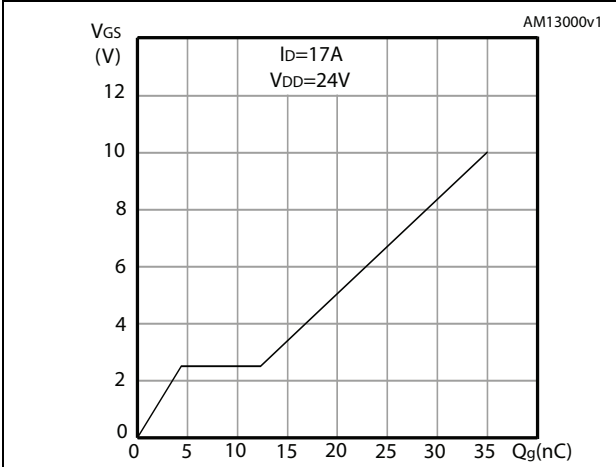


Figure 9. Capacitance variations

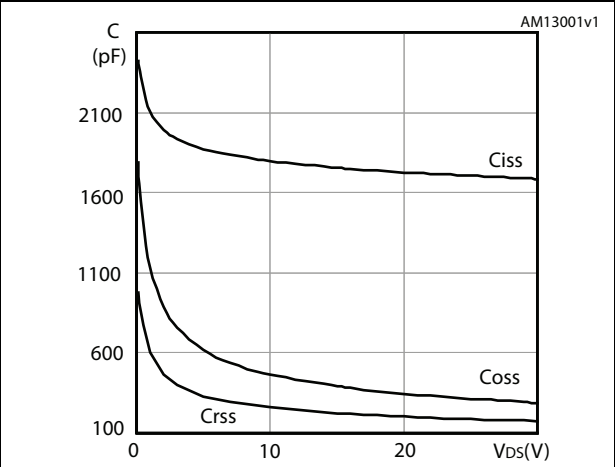


Figure 10. Normalized gate threshold voltage vs temperature

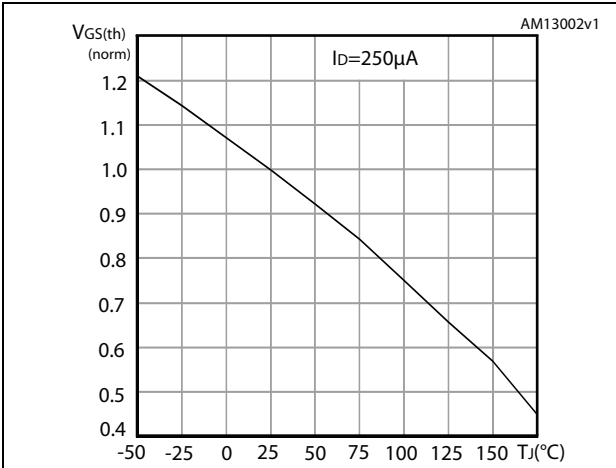


Figure 11. Normalized on-resistance vs temperature

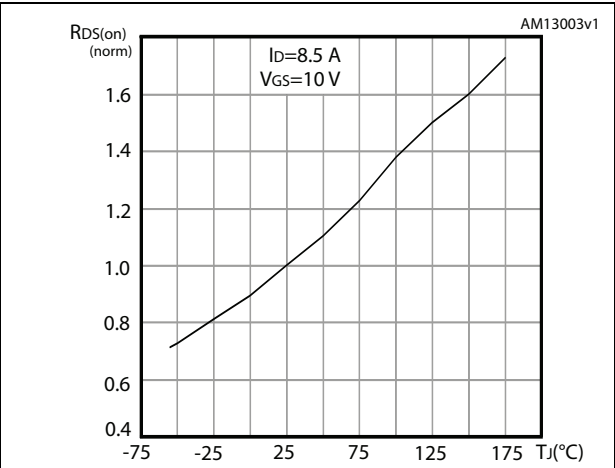
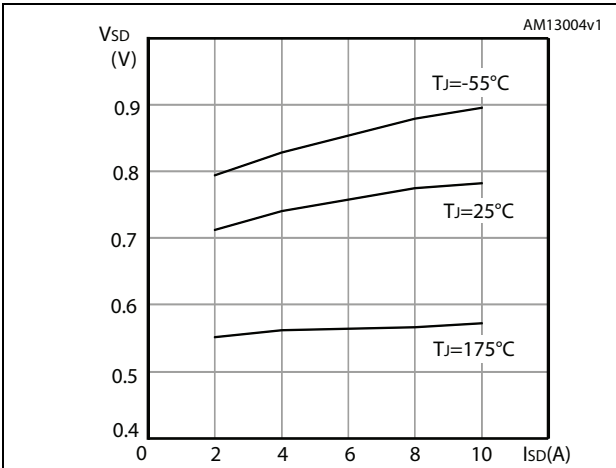


Figure 12. Source-drain diode forward characteristics



3 Test circuits

Figure 13. Switching times test circuit for resistive load

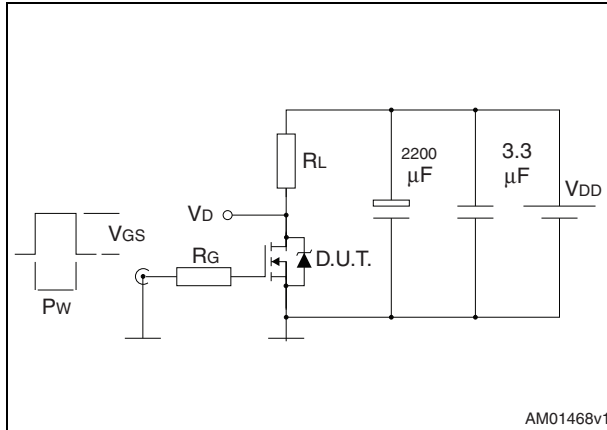


Figure 14. Gate charge test circuit

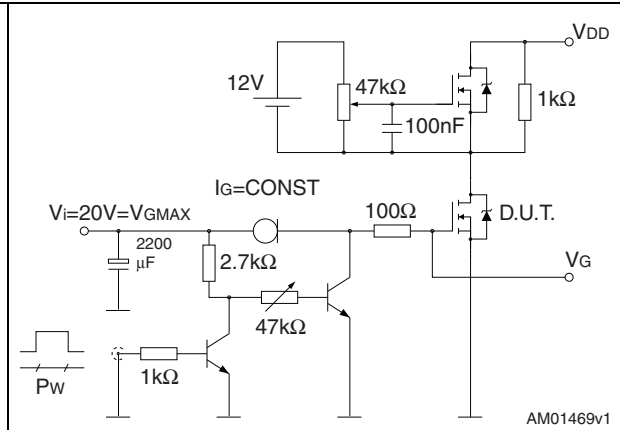


Figure 15. Test circuit for inductive load switching and diode recovery times

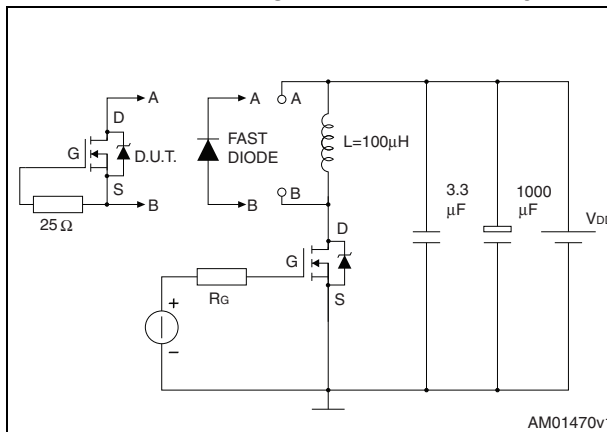


Figure 16. Unclamped inductive load test circuit

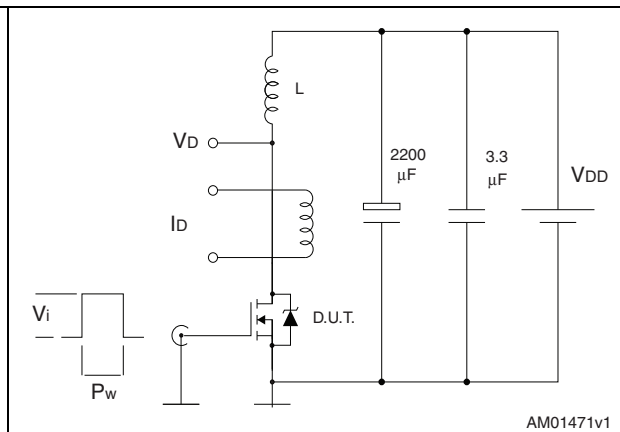


Figure 17. Unclamped inductive waveform

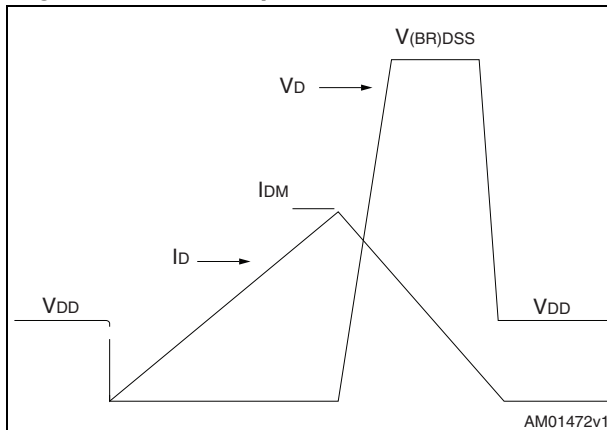
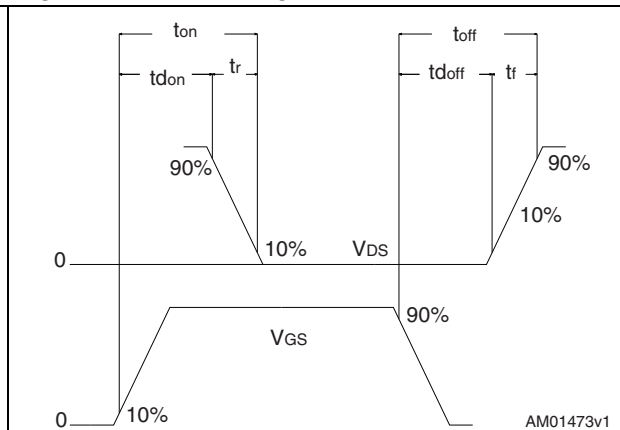


Figure 18. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 8. PowerFLAT™ 3.3 x 3.3 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.70	0.80	0.90
b	0.25	0.30	0.39
c	0.14	0.15	0.20
D	3.10	3.30	3.50
D1	3.05	3.15	3.25
D2	2.15	2.25	2.35
e	0.55	0.65	0.75
E	3.10	3.30	3.50
E1	2.90	3.00	3.10
E2	1.60	1.70	1.80
H	0.25	0.40	0.55
K	0.65	0.75	0.85
L	0.30	0.45	0.60
L1	0.05	0.15	0.25
L2			0.15
∅	8°	10°	12°

Figure 19. PowerFLAT™ 3.3 x 3.3 drawing

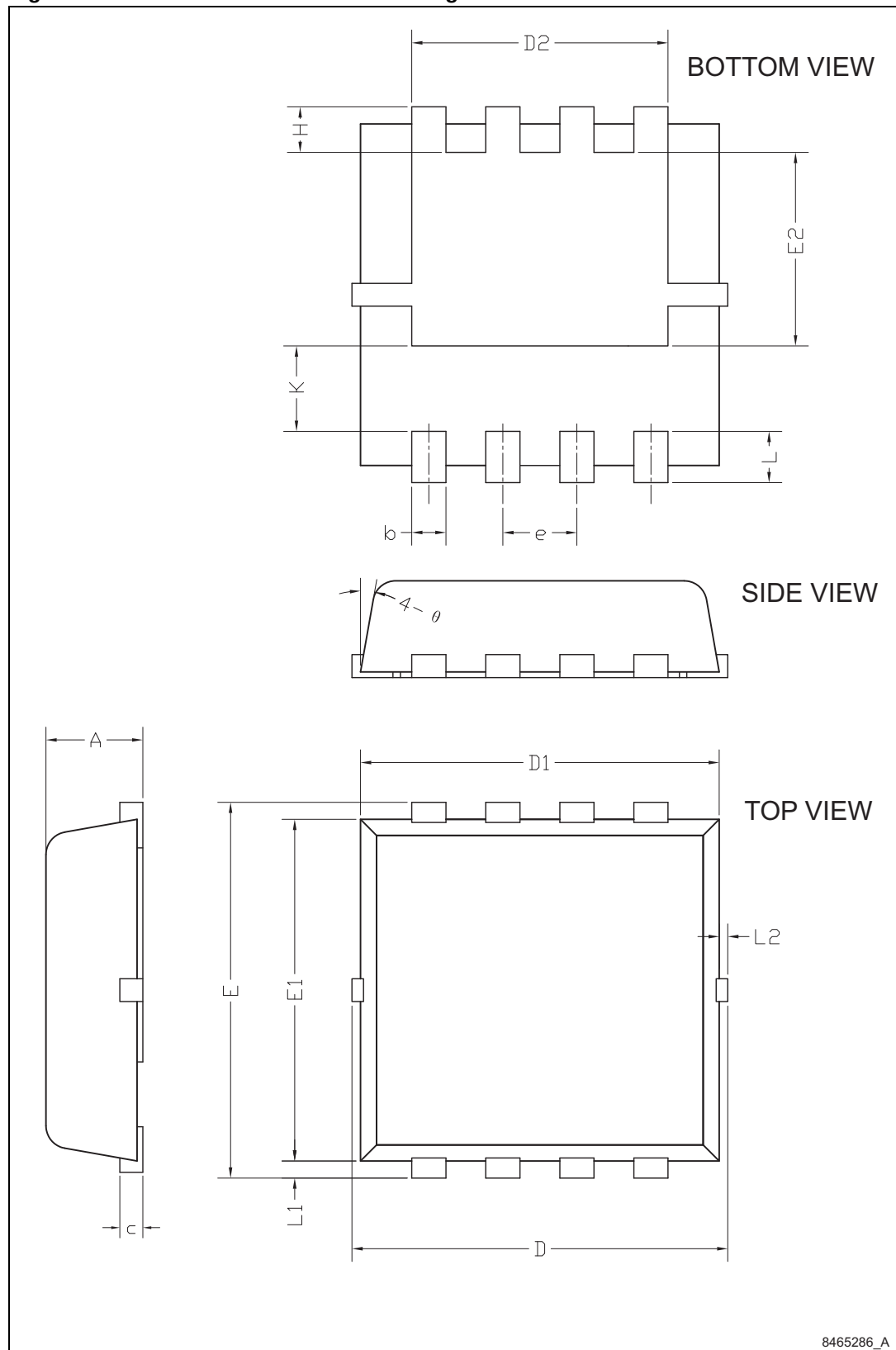
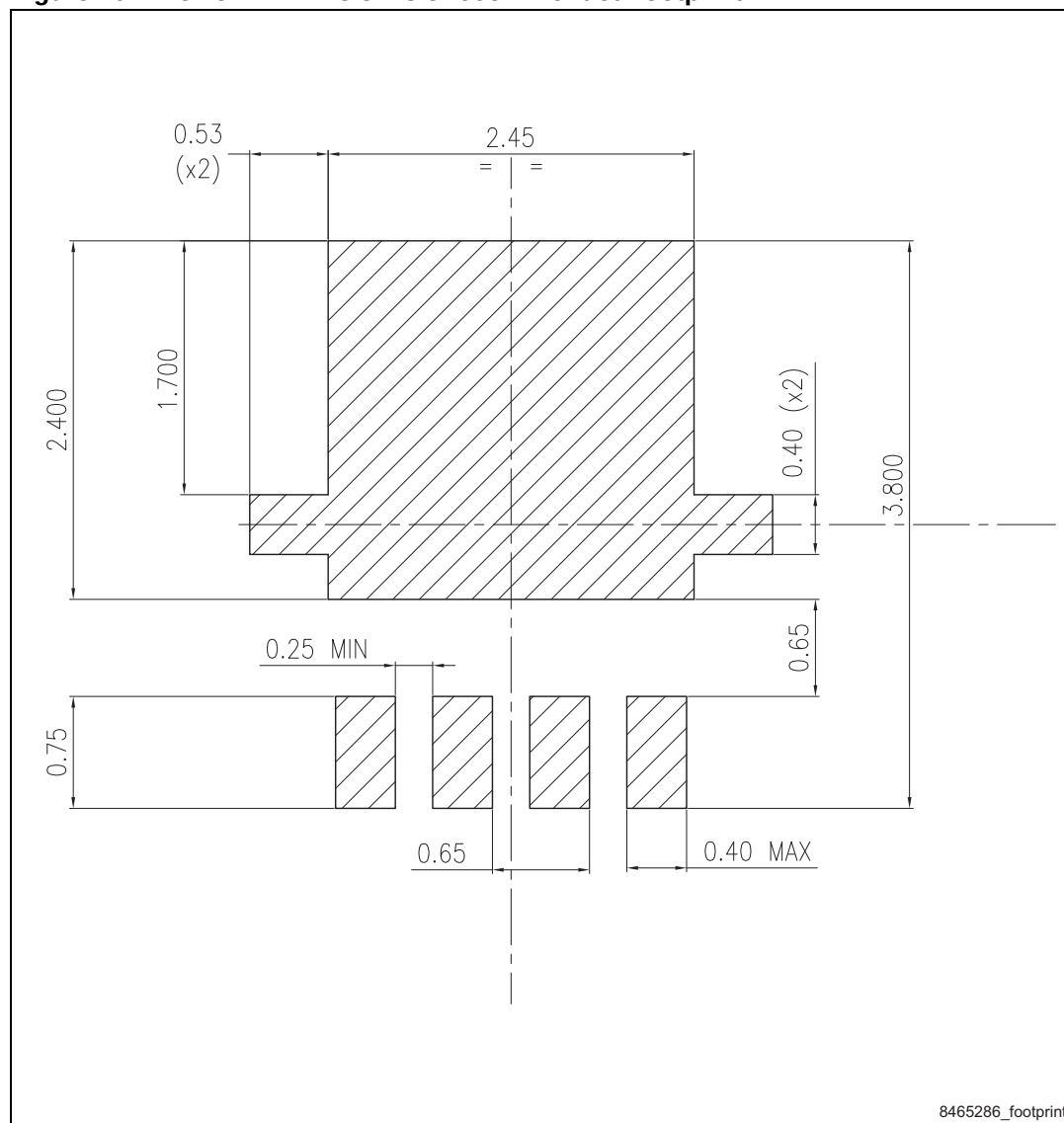


Figure 20. PowerFLAT™ 3.3 x 3.3 recommended footprint



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
24-Mar-2009	1	First release.
06-Jul-2010	2	Updated Table 4: On/off states .
10-Nov-2010	3	Document status promoted from preliminary data to datasheet.
17-Jun-2013	4	– Updated: Figure 1, silhouette in cover page and Section 4: Package mechanical data – Minor text changes

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